

Specification for Approval

Date: 2017/01/20

Customer: 深圳臺慶

	TAI-TECH P/N:	FPI0504F- SERIES
	CUSTOMER P/N:	
	DESCRIPTION:	
	QUANTITY:	pcs
	REMARK:	
	Cu	stomer Approval Feedback
TAO-YUAN HSIEN, TAIWAN, TEL: +886-3-4641148 FAX http://www.tai-tech.com.tw E-mail: sales@tai-tech.com.	lectronics Co., Ltd H INDUSTRIAL DISTRICT, YANG-N R.O.C. +886-3-4643565	iei, Sales De
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Mike Yang	Jack Chan	Sharon Ho

TAI-TECH

SMD Type Power Inductor

	ECN HISTORY LIST					
REV	DATE	DESCRIPTION	APPROVED	CHECKED	DRAWN	
1.0	17/01/20	新 發 行	楊祥忠	詹偉特	何秦芝	
備						
註						

SMD Type Power Inductor

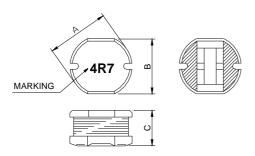
1. Features

- 1.Excellent solderability and high heat resistance.
- 2.Excellent terminal strength construction.
- 3. Packed in embossed carrier tape and can be used by automatic mounting machine.
- 4.100% Lead(Pb) & Halogen-Free and RoHS compliant.



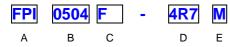


2. Dimension



Size	A(mm)	B(mm)	C(mm)
FPI 0504	5.80±0.3	5.20±0.3	4.50±0.3

3. Part Numbering



A: Series

B: Dimension

C: Lead free type Black marking
D: Inductance 4R7=4.7uH

E: Inductance Tolerance K=±10%, M=±20%

4. Specification

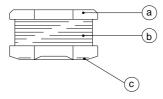
TAI-TECH Part Number	Inductance (uH)	Tolerance (%)	Test Frequency (Hz)	DCR (Ω) max.	IDC (A) max.
FPI 0504F-1R0M	1.0	± 20%	1V/7.96M	0.018	3.50
FPI 0504F-1R4M	1.4	± 20%	1V/7.96M	0.020	3.50
FPI 0504F-1R8M	1.8	± 20%	1V/7.96M	0.025	3.00
FPI 0504F-2R2M	2.2	± 20%	1V/7.96M	0.030	2.80
FPI 0504F-2R7M	2.7	± 20%	1V/7.96M	0.035	2.60
FPI 0504F-3R3M	3.3	± 20%	1V/7.96M	0.040	2.50
FPI 0504F-3R9M	3.9	± 20%	1V/7.96M	0.050	2.30
FPI 0504F-4R7M	4.7	± 20%	1V/7.96M	0.060	2.60
FPI 0504F-5R6M	5.6	± 20%	1V/7.96M	0.070	2.40
FPI 0504F-6R8M	6.8	± 20%	1V/7.96M	0.080	2.20
FPI 0504F-8R2M	8.2	± 20%	1V/7.96M	0.080	2.00
FPI 0504F-100M	10	± 20%	1V/2.52M	0.090	1.80
FPI 0504F-120M	12	± 20%	1V/2.52M	0.100	1.60
FPI 0504F-150M	15	± 20%	1V/2.52M	0.120	1.50
FPI 0504F-180M	18	± 20%	1V/2.52M	0.150	1.40
FPI 0504F-220M	22	± 20%	1V/2.52M	0.180	1.30
FPI 0504F-270M	27	± 20%	1V/2.52M	0.220	1.20
FPI 0504F-330M	33	± 20%	1V/2.52M	0.260	1.00
FPI 0504F-390M	39	± 20%	1V/2.52M	0.300	0.90
FPI 0504F-470M	47	± 20%	1V/2.52M	0.350	0.85
FPI 0504F-560M	56	± 20%	1V/2.52M	0.400	0.80
FPI 0504F-680M	68	± 20%	1V/2.52M	0.450	0.70
FPI 0504F-820M	82	± 20%	1V/2.52M	0.500	0.70
FPI 0504F-101M	100	± 20%	1V/1K	0.700	0.60
FPI 0504F-121M	120	± 20%	1V/1K	0.750	0.60
FPI 0504F-151M	150	± 20%	1V/1K	0.900	0.55
FPI 0504F-181M	180	± 20%	1V/1K	1.100	0.50
FPI 0504F-221M	220	± 20%	1V/1K	1.200	0.40
FPI 0504F-271M	270	± 20%	1V/1K	1.500	0.25
FPI 0504F-331M	330	± 20%	1V/1K	3.000	0.22
FPI 0504F-391M	390	± 20%	1V/1K	3.500	0.20
FPI 0504F-471M	470	± 20%	1V/1K	4.000	0.19
FPI 0504F-561M	560	± 20%	1V/1K	4.000	0.18
FPI 0504F-681M	680	± 20%	1V/1K	4.500	0.15

^{*} IDC Test

Isat : Based on inductance change $\ (\triangle L/L0: \le -35\%) \ @$ ambient temp. 25%

For all FPI series ,when a IDC current is applied, the temperature rised of the parts is less than 40 degree C

5. Material List



No.	Item	Material
1	Core	Ferrite DR Core
2	Wire	Enamelled Copper wire
3	Terminal	Ag+Ni+Sn

6. Schematic Diagram

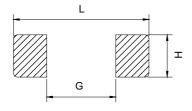


7. Reliability and Test Condition

Item	Performance	Test Condition
Operating temperature	-40~+125℃ (Including self - temperature rise)	
Storage temperature	-40~+125℃ (on board)	
Electrical Performance Te	est	
		HP4284A,CH11025,CH3302,CH1320,CH1320S
Inductance	Refer to standard electrical characteristics list.	LCR Meter.
DCR		CH16502, Agilent33420A Micro-Ohm Meter.
		Saturation DC Current (Isat) will cause L0
Saturation Current (Isat)	∆L≦35%	to drop △L(%).
		Heat Rated Current (Irms) will cause the coil temperature rise
		△T(°C)
Heat Rated Current (Irms)	Approximately △T40°C	1.Applied the allowed DC current
		Temperature measured by digital surface thermometer
Reliability Test		
Life Test		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles) Temperature: 125±2°C (Inductor) Applied current: rated current Duration: 1000±12hrs Measured at room temperature after placing for 24±2 hrs
Load Humidity		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles Humidity: 85±2*R.H, Temperature: 85°C±2°C Duration: 1000hrs Min. with 100% rated current Measured at room temperature after placing for 24±2 hrs
Moisture Resistance	Appearance: No damage. Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles 1. Baked at50℃ for 25hrs, measured at room temperature after placing for 4 hrs. 2. Raise temperature to 65±2℃ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25℃ in 2.5hrs. 3. Raise temperature to 65±2℃ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25℃ in 2.5hrs. 4. Keep at 25℃ for 2 hrs then keep at -10℃ for 3 hrs 4. Keep at 25℃ 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1-2 hrs.
Thermal shock		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles Condition for 1 cycle Step1: -40±2°C 30±5min Step2: 25±2°C ≤0.5min Step3: 125±2°C 30±5min Number of cycles: 500 Measured at room temperature after placing for 24±2 hrs

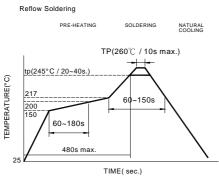
Item	Performance	Test Condition			
Vibration		Oscillation Frequency: 10 ~ 2K ~ 10Hz for 20 minutes Equipment: Vibration checker Total Amplitude:1.52mm±10% Testing Time: 12 hours(20 minutes, 12 cycles each of 3 orientations).			
Shock	Appearance: No damage. Inductance: within±10% of initial value Q: Shall not exceed the specification value.	Type Peak Normal Wave change (y')ft/sec			
	RDC: within ±15% of initial value and shall not exceed the specification value	SMD 50 11 Half-sine 11.3 Lead 50 11 Half-sine 11.3			
Bending		Shall be mounted on a FR4 substrate of the following dimensions: >=0805 inch(2012mm):40x100x1.2mm <0805 inch(2012mm):40x100x0.8mm Bending depth: >=0805 inch(2012mm):1.2mm <0805 inch(2012mm):0.8mm duration of 10 sec.			
Solderability	More than 95% of the terminal electrode should be covered with solder.	Preheat: 150℃,60sec.。 Solder: Sn96.5% Ag3% Cu0.5% Temperature: 245±5℃。 Flux for lead free: Rosin. 9.5%。 Dip time: 4±1sec。 Depth: completely cover the termination			
Resistance to Soldering Heat		Number of heat cycles: 1 Temperature (°C) Time(s) Temperature ramp/immersion and emersion rate 260 ±5(solder temp) 10 ±1 25mm/s ±6 mm/s			
Terminal Strength	Appearance: No damage. Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles With the component mounted on a PCB with the device to be tested, apply a force (>0805 inch(2012mm):1kg, <=0805 inch(2012mm):0.5kg)to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested.			
		DUT wide substrate press tool			

8. Recommended PC Board Pattern



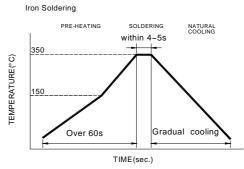
Chin sins	Land Patterns For Reflow Soldering				
Chip size	L(mm) G(mm) H(mm)				
FPI0504	6	1.7	5.5		

9. Soldering



Reflow times: 3 times max.

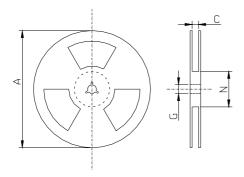
Fig.1



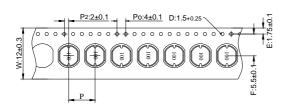
Iron Soldering times: 1 times max.

Fig.2

10. Packaging Information



Style	A(mm)	C(mm)	G(mm)	N(mm)
13"X12mm	330	14 ⁺⁰	13.5±0.5	50 ⁻⁰



Size	W(mm)	P(mm)	D(mm)	Packaging Qty(pcs)
0504	12±0.3	8±0.1	1.5±0.25	1,500

Application Notice

- Storage Conditions(component level)
- To maintain the solderability of terminal electrodes:
- 1. TAI-TECH products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
- 3. Recommended products should be used within 12 months form the time of delivery.
- 4. The packaging material should be kept where no chlorine or sulfur exists in the air.
- Transportation
 - 1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- 2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
- 3. Bulk handling should ensure that abrasion and mechanical shock are minimized.



Test Report

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日期(Date): 2016/07/06

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西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

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(耀鑚科技股份有限公司 / YOSONIC TECHNOLOGY CO., LTD.)

(慶邦電子元器件 (泗洪) 有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號 / NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN,

(江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA) (桃園市中壢區中壢工業區長春六路15號 / NO. 15, CHANGCHUN 6TH RD., JHONGLI DISTRICT, TAOYUAN CITY 320, TAIWAN) (中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P, R, CHINA)

以下測試樣品係由申請廠商所提供及確認 (The following sample(s) was/were submitted and identified by/on behalf of the applicant as):

樣品名稱(Sample Description)

WINDING POWER INDUCTOR / SMD POWER INDUCTOR

樣品型號(Style/Item No.)

LQC . LQN . FPI . FPIP SERIES

收件日期(Sample Receiving Date)

2016/06/29

測試期間(Testing Period)

2016/06/29 TO 2016/07/06

測試結果(Test Results) : 請見下一頁 (Please refer to next pages).



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測試結果(Test Results)

測試部位(PART NAME)No.1

整體混測 (MIXED ALL PARTS)

測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	方法偵測 極限值 (MDL)	結果 (Result) No.1
鍋 / Cadmium (Cd)	mg/kg	參考IEC 62321-5 (2013),以感應耦合 電漿原子發射光譜儀檢測. / With	2	n. đ.
鉛 / Lead (Pb)	mg/kg	reference to IEC 62321-5 (2013) and performed by ICP-AES.	2	n. d.
汞 / Mercury (Hg)	mg/kg	參考IEC 62321-4 (2013),以感應耦合 電漿原子發射光譜儀檢測. / With reference to IEC 62321-4 (2013) and performed by ICP-AES.	2	n. d.
六價鉻 / Hexavalent Chromium Cr(VI)	mg/kg	参考IEC 62321 (2008),以UV-VIS檢 測. / With reference to IEC 62321 (2008) and performed by UV-VIS.	2	n. d.
六溴環十二烷及所有主要被辨別出的異構物 / Hexabromocyclododecane (HBCDD) and all major diastereoisomers identified (α - HBCDD, β - HBCDD, γ - HBCDD) (CAS No.: 25637-99-4 and 3194-55-6 (134237-51-7, 134237-50-6, 134237-52-8))	mg/kg	參考IEC 62321 (2008),以氣相層析/ 質譜儀檢測. / With reference to IEC 62321 (2008). Analysis was performed by GC/MS.	5	n, d.

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測試項目	單位	测試方法(Nathod)	方法偵測 極限值	結果 (Result)
(Test Items)	(Unit)	(Method)	(MDL)	No. 1
多溴聯苯總和 / Sum of PBBs	mg/kg		_	n. d.
一溴聯苯 / Monobromobiphenyl	mg/kg]	5	n. d.
二溴聯苯 / Dibromobiphenyl	mg/kg]	5	n. d.
三溴聯苯 / Tribromobiphenyl	mg/kg		5	n. d.
四溴聯苯 / Tetrabromobiphenyl	mg/kg		5	n. d.
五溴聯苯 / Pentabromobiphenyl	mg/kg] [5	n. d.
六溴聯苯 / Hexabromobiphenyl	mg/kg		5	n. d.
七溴聯苯 / Heptabromobiphenyl	mg/kg	·	5	n. d.
八溴聯苯 / Octabromobiphenyl	mg/kg		5	n. d.
九溴聯苯 / Nonabromobiphenyl	mg/kg	參考IEC 62321-6 (2015),以氣相層析 /質譜儀檢測. / With reference to IEC 62321-6 (2015) and performed by GC/MS.	5	n. d.
十溴聯苯 / Decabromobiphenyl	mg/kg		5	n. d.
多溴聯苯醚總和 / Sum of PBDEs	mg/kg		-	n. d.
一溴聯苯醚 / Monobromodiphenyl ether	mg/kg		5	n. d.
二溴聯苯醚 / Dibromodiphenyl ether	mg/kg		5	n, d.
三溴聯苯醚 / Tribromodiphenyl ether	mg/kg]	5	n. d.
四溴聯苯醚 / Tetrabromodiphenyl ether	mg/kg		5	n. d.
五溴聯苯醚 / Pentabromodiphenyl ether	mg/kg		5	n. đ.
六溴聯苯醚 / Hexabromodiphenyl ether	mg/kg		5	n. d.
七溴聯苯醚 / Heptabromodiphenyl ether	mg/kg		5	n. d.
八溴聯苯醚 / Octabromodiphenyl ether	mg/kg		5	n. d.
九溴聯苯醚 / Nonabromodiphenyl ether	mg/kg		5	n. d.
十溴聯苯醚 / Decabromodiphenyl ether	mg/kg		5	n. d.

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測試項目 (Test Items)	單位 (Unit)	测試方法 (Method)	方法偵測 極限值	結果 (Result)
(Test Troms)	(0111 0)	· (inc thou)	(MDL)	No. 1
鄰苯二甲酸丁苯甲酯 / BBP (Buty1 Benzyl phthalate) (CAS No.: 85-68-7)	mg/kg	参考IEC 62321-8/CD (2013),以氣相層析儀/質譜儀檢測./ With reference to IEC 62321-8/CD (2013). Analysis was performed by GC/MS.	50	n. d.
鄰苯二甲酸二丁酯 / DBP (Dibutyl phthalate) (CAS No.: 84-74-2)	mg/kg		50	n, d,
「本本二甲酸二 (2-乙基己基)酯 / DEHP (Di- (2-ethylhexyl) phthalate) (CAS No.: 117-81-7)	mg/kg		50	n. d.
鄰苯二甲酸二異丁酯 / DIBP (Di- isobutyl phthalate) (CAS No.: 84-69- 5)	mg/kg		50	n. d.
鄭苯二甲酸二異癸酯 / DIDP (Di- isodecyl phthalate) (CAS No.: 26761- 40-0; 68515-49-1)	mg/kg		50	n. d.
鄰苯二甲酸二異壬酯 / DINP (Di- isononyl phthalate) (CAS No.: 28553- 12-0; 68515-48-0)	mg/kg		50	n. d.
鄰苯二甲酸二正辛酯 / DNOP (Di-n-octyl phthalate) (CAS No.: 117-84-0)	mg/kg		50	n. d.
鄰苯二甲酸二正己酯 / DNHP (Di-n-hexyl phthalate) (CAS No.: 84-75-3)	mg/kg		50	n. d.
鄰苯二甲酸二戊酯 / Di-n-pentyl phthalate (CAS No.: 131-18-0)	mg/kg		50	n. d.

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測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	方法偵測 極限値 (MDL)	結果 (Result) No.1
鹵素 / Halogen				
鹵素(氟)/ Halogen-Fluorine (F) (CAS No.: 14762-94-8)	mg/kg		50	n. d.
鹵素(氣)/ Halogen-Chlorine (C1) (CAS No.: 22537-15-1)	mg/kg	参考BS EN 14582 (2007),以離子層析 儀分析. / With reference to BS EN 14582 (2007). Analysis was performed by IC.	50	n, d,
鹵素(溴)/ Halogen-Bromine (Br) (CAS No.: 10097-32-2)	mg/kg		50	n. d.
鹵素(碘)/ Halogen-Iodine(I)(CAS No.: 14362-44-8)	-mg/kg		50	n. d.
绨 / Antimony (Sb)	mg/kg	参考US EPA 3052 (1996),以感應耦合電漿原子發射光譜儀檢測. / With	2	n. d.
鈹 / Beryllium (Be)	mg/kg	reference to US EPA 3052 (1996). Analysis was performed by ICP-AES.	2	n. d.

備註(Note):

- 1. mg/kg = ppm : 0.1wt% = 1000ppm
- 2. n.d. = Not Detected (未檢出)
- 3. MDL = Method Detection Limit (方法偵測極限值)
- 4. "-" = Not Regulated (無規格值)
- 5. 樣品的測試是基於申請人要求混合測試,報告中的混合測試結果不代表其中個別單一材質的含量. (The samples was/were analyzed on behalf of the applicant as mixing sample in one testing. The above results was/were only given as the informality value.)

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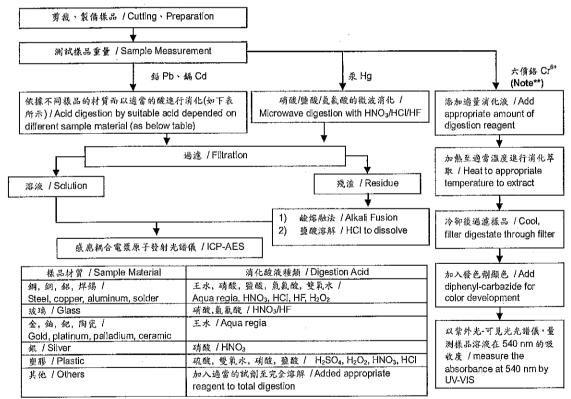
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根據以下的流程圖之條件,樣品已完全溶解。(六價絡測試方法除外)

These samples were dissolved totally by pre-conditioning method according to below flow chart. (Cr⁶⁺ test method excluded)

- 测試入員:王志瑋 / Technician: JR Wang
- 測試負責人:張啟興 / Supervisor: Troy Chang



Note** (For IEC 62321)

- (1) 針對非金屬材料加入鹼性消化液,加熱至 90~95℃萃取. / For non-metallic material, add alkaline digestion reagent and heat to
- (2) 針對金屬材料加入純水、加熱至沸腾萃取. / For metallic material, add pure water and heat to boiling.

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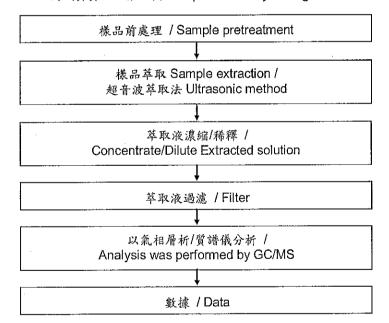
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六溴環十二烷分析流程圖 / Analytical flow chart - HBCDD

- 測試人員:涂雅苓 / Technician: Yaling Tu
- 測試負責人:張啟興 / Supervisor: Troy Chang



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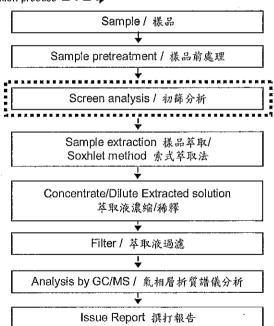
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多溴聯苯/多溴聯苯醚分析流程圖 / Analytical flow chart - PBB/PBDE

測試人員:涂雅苓 / Technician: Yaling Tu

測試負責人:張啟興 / Supervisor: Troy Chang

初次測試程序 / First testing process . 選擇性篩檢程序 / Optional screen process . 確認程序 / Confirmation process - - - →



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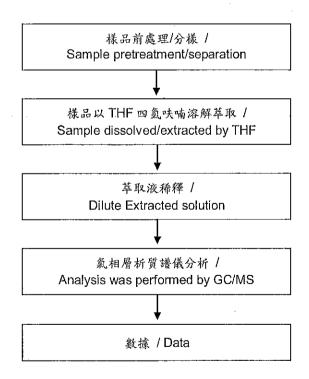
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可塑劑分析流程圖 / Analytical flow chart - Phthalate

- 測試人員:徐毓明 / Technician: Andy Shu
- 測試負責人:張啟興 / Supervisor nt: Troy Chang

【測試方法/Test method: IEC 62321-8】



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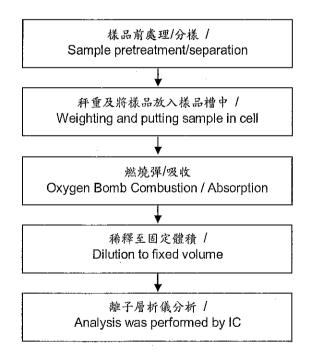
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鹵素分析流程圖 / Analytical flow chart - Halogen

測試人員:陳恩臻 / Technician: Rita Chen

測試負責人:張啟興 / Supervisor: Troy Chang



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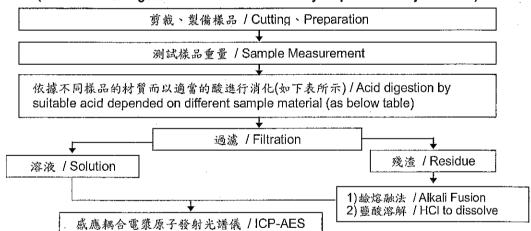
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> 根據以下的流程圖之條件,樣品已完全溶解。 / These samples were dissolved totally by pre-conditioning method according to below flow chart.

- 測試人員: 王志瑋 / Technician: JR Wang
- 測試負責人:張啟興 / Supervisor: Troy Chang

元素以 ICP-AES 分析的消化流程圖 (Flow Chart of digestion for the elements analysis performed by ICP-AES)



鋼,銅,鋁,焊錫 / Steel, copper, aluminum, solder	王水,硝酸,鹽酸,氫氯酸,雙氧水 / Aqua regia, HNO ₃ , HCI, HF, H ₂ O ₂
玻璃 / Glass	硝酸,氫氟酸 / HNO ₃ /HF
金,鲌,鲃,陶瓷 / Gold, platinum, palladium, ceramic	王水 / Aqua regia
銀 / Silver	硝酸 / HNO ₃
塑膠 / Plastic	硫酸,雙氧水,硝酸,鹽酸 / H ₂ SO ₄ , H ₂ O ₂ , HNO ₃ , HCl
其他 / Others	加入適當的試劑至完全溶解 / Added appropriate reagent to total digestion

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(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO. LTD.)

(耀鑽科技股份有限公司 / YOSONIC TECHNOLOGY CO., LTD.)

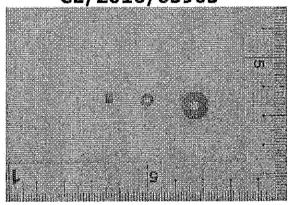
(慶邦電子元器件 (泗洪) 有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號 / NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.

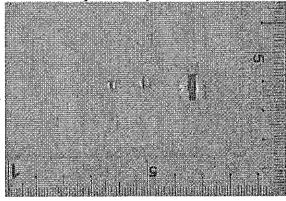
(江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA) 「桃園市中壢區中壢工業區長春六路15號 / NO. 15, CHANGCHUN 6TH RD., JHONGLI DISTRICT, TAOYUAN CITY 320, TAIWAN) — (中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD,ECONOMIC DEVELOPMENT ZONE,SIHONG COUNTY,SUQIANCITY,JIANGSU PROVINCE,P,R,CHINA)

* 照片中如有箭頭標示,則表示為實際檢測之樣品/部位. * (The tested sample / part is marked by an arrow if it's shown on the photo.)

CE/2016/65905



CE/2016/65905



** 報告結尾 (End of Report) **

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